

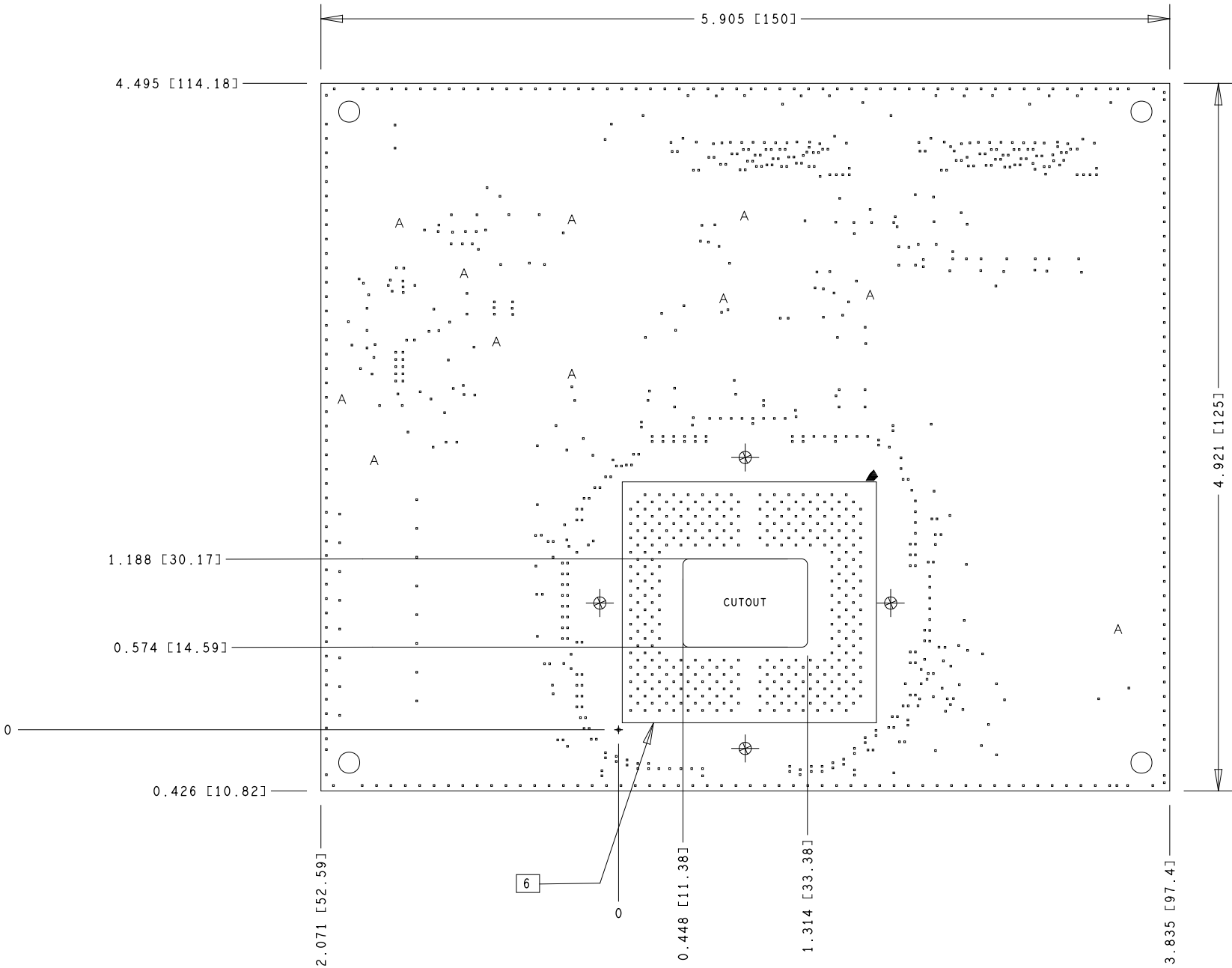
DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	FINISHED_SIZE	TOLERANCE_DRILL	PLATED	QTY
•	12.0	+3.0 / -12.0	PLATED	1109
A	63.0	+3.0 / -3.0	PLATED	11
△	60.2	+2.0 / -2.0	NON-PLATED	9
+	78.7	+2.0 / -2.0	NON-PLATED	1
○	146.0	+3.0 / -3.0	NON-PLATED	4
⊕	189.0	+3.0 / -3.0	NON-PLATED	4

FAB NOTES:

1. ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010". DIMENSIONS ARE FOR REFERENCE ONLY. USE ARTWORK FOR ACCURATE MEASUREMENT OF THE BOARD OUTLINE.
2. THE PWB SHALL BE FABRICATED TO IPC-6011 AND IPC-6012, CLASS 2, TYPE 3. WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
3. BOARD MATERIAL SHALL BE 180 Tg/340 Td ISOLA FR-370HR OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. RoHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
4. BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD. ALL BOARDS MUST MEET OR EXCEED UL94V-0 REQUIREMENTS. PCB MUST BEAR THE UL94V-0 REGISTERED MATERIAL ID NUMBER.
5. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH WITH A MINIMUM ANNULAR RING OF .001 INCH.
6. OVERALL BOARD THICKNESS TO BE .062 +/- .10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
7. INNER PLANE LAYERS TO BE 1/2 OZ. COPPER. INNER SIGNAL LAYERS TO BE 1/2 OZ. COPPER. OUTER LAYERS TO BE 1/2 OZ. COPPER + PLATING.
8. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
9. ALL HOLES ARE ON A 0.0001 GRID EXCEPT THOSE INDICATED.
10. MAXIMUM RATED VOLTAGE BETWEEN CONDUCTORS SHALL BE 65 VOLTS PEAK.
11. NO BREAKOUT ALLOWED ON PLATED THROUGH HOLES.
12. FOIL OUTER OPTIONAL.
13. INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994
14. TEARDROP VIAS AS NECESSARY.
15. THEIVING IS NOT ALLOWED.

PROCESS NOTES:

1. EXCEPT AS NOTED BELOW, ALL EXPOSED CONDUCTORS ON BOTH SIDES PWB SHALL BE ELECTROPLATED GOLD (5-15 MICROINCHES) OVER ELECTROPLATED NICKEL (50 MIN MICROINCHES).
2. APPLY LPI SOLDERMASK.
→ COLOR: RED. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
3. FABRICATION VENDOR IS ALLOWED TO INCREASE SOLDERMASK COMPONENT PADS BY A MAXIMUM 1 MIL ON EACH SIDE OVER THE COPPER PAD IN ORDER TO MEET TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
4. APPLY LPI SILKSCREEN OR EQUIVALENT BOTH SIDES PER THE ART. COLOR: WHITE.
5. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
6. PLATE INDICATED PAD AREAS WITH A MINIMUM OF 30, MAXIMUM OF 50 MICROINCHES ELECTROLYTIC HARD GOLD OVER A MINIMUM OF 50 MICROINCHES OF ELECTROLYTIC NICKEL.



Primary Side Show



TEXAS INSTRUMENTS		
BOARD NAME:	DLPLCR99EVM	DESCRIPTION: FAB DRAWING
PROJECT #:	DLP019	DATE: 12 OCT 2023 REVISION: Rev. F

CONTROLLED IMPEDANCE

LAYER STACKUP	50 OHMS SINGLE ENDED +/-10%	WIDTH/SPACING 100 OHMS DIFFERENTIAL +/-10%
LAYER 1 - PRIMARY SIDE/GND FILL		
LAYER 2 - SIGNAL	0.0057"	0.0048/0.0074
LAYER 3 - GND PLANE		
LAYER 4 - SIGNAL	0.0065	0.0050/0.0072
LAYER 5 - GND PLANE		
LAYER 6 - SIGNAL	0.0047"	0.0042/0.0080
LAYER 7 - GND PLANE		
LAYER 8 - SECONDARY SIDE/PWR FILL		